# DIE/LAYOUT (B-STEP)

![Die Layout Diagram]

## DIE/WAFER CHARACTERISTICS

<table>
<thead>
<tr>
<th>Fabrication Attributes</th>
<th>General Die Information</th>
</tr>
</thead>
<tbody>
<tr>
<td>Physical Die Identification</td>
<td>DS90LV011AB</td>
</tr>
<tr>
<td>Die Step</td>
<td>B</td>
</tr>
<tr>
<td>Bond Pad Opening Size (min)</td>
<td>102μm x 102μm</td>
</tr>
<tr>
<td>Bond Pad Metalization</td>
<td>Al_0.5%Cu</td>
</tr>
<tr>
<td>Passivation</td>
<td>PECVD/DOX+NITRIDE</td>
</tr>
<tr>
<td>Physical Attributes</td>
<td></td>
</tr>
<tr>
<td>Wafer Diameter</td>
<td>200mm</td>
</tr>
<tr>
<td>Back Side Metal</td>
<td>BARE BACK</td>
</tr>
<tr>
<td>Die Size (Drawn)</td>
<td>889μm x 838μm</td>
</tr>
<tr>
<td>Back Side Connection</td>
<td>GND</td>
</tr>
<tr>
<td>35.0mil x 33.0mil</td>
<td></td>
</tr>
<tr>
<td>Thickness</td>
<td>254μm Nominal</td>
</tr>
<tr>
<td>Min Pitch</td>
<td>285μm Nominal</td>
</tr>
</tbody>
</table>

**Special Assembly Requirements:**

Note: Actual die size is rounded to the nearest micron.
# DS90LV011A MDA MWA

## 3V LVDS SINGLE HIGH SPEED CMOS DIFFERENTIAL DRIVER

### Die Bond Pad Coordinate Locations (B-Step)

(Referenced to die center, coordinates in μm) **NC** = No Connection, **N.U.** = Not Used

<table>
<thead>
<tr>
<th>SIGNAL</th>
<th>PAD#</th>
<th>X/Y COORDINATES</th>
<th>PAD SIZE</th>
</tr>
</thead>
<tbody>
<tr>
<td>NAME</td>
<td>NUMBER</td>
<td>X</td>
<td>Y</td>
</tr>
<tr>
<td>VDD</td>
<td>1</td>
<td>-49</td>
<td>280</td>
</tr>
<tr>
<td>GND</td>
<td>2</td>
<td>-304</td>
<td>-7</td>
</tr>
<tr>
<td>TTL IN</td>
<td>3</td>
<td>-49</td>
<td>-280</td>
</tr>
<tr>
<td>OUT +</td>
<td>4</td>
<td>236</td>
<td>-280</td>
</tr>
<tr>
<td>OUT -</td>
<td>5</td>
<td>236</td>
<td>280</td>
</tr>
</tbody>
</table>
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